



THE DATASHEET OF 2N7002KDW-TP

Features

- ESD Protected Up To 2KV (HBM)
- Trench MV MOSFET Technology
- Moisture Sensitivity Level 1
- Halogen Free. "Green" Device (Note1)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

Maximum Ratings

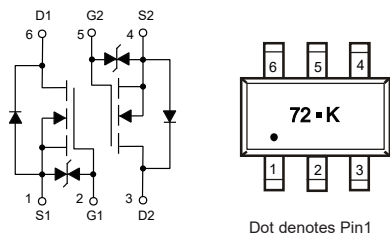
- Operating Junction Temperature Range: -55°C to +150°C
- Storage Temperature: -55°C to +150°C
- Thermal Resistance: 416°C/W Junction to Ambient^(Note2)

Parameter		Symbol	Rating	Unit
Drain-Source Voltage		V _{DS}	60	V
Gate-Source Voltage		V _{GS}	±20	V
Continuous Drain Current	T _A =25°C	I _D	340	mA
	T _A =70°C		272	
Pulsed Drain Current ^(Note 3)		I _{DM}	1.36	A
Total Power Dissipation ^(Note 4)		P _D	300	mW

Note:

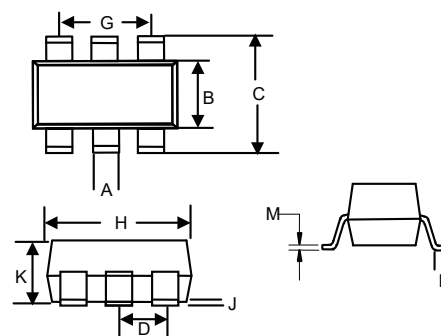
1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
2. The value of $R_{\theta JA}$ is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$.
3. Repetitive rating; pulse width limited by max. junction temperature.
4. P_D is based on max. junction temperature, using junction-ambient thermal resistance.

Internal Structure and Marking Code



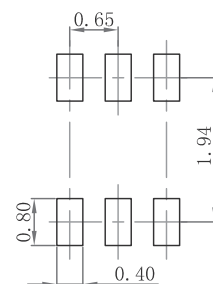
DUAL N-CHANNEL MOSFET

SOT-363



DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.006	0.014	0.15	0.35	
B	0.045	0.053	1.15	1.35	
C	0.079	0.096	2.00	2.45	
D	0.026		0.65		TYP.
G	0.047	0.055	1.20	1.40	
H	0.071	0.087	1.80	2.20	
J	-----	0.004	-----	0.10	
K	0.031	0.043	0.80	1.10	
L	0.010	0.018	0.26	0.46	
M	0.003	0.006	0.08	0.15	

SUGGESTED SOLDER PAD LAYOUT



Electrical Characteristics @ 25°C (Unless Otherwise Specified)

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =250μA	60			V
Gate-Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =1mA	1.0	1.5	2.5	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =48V, V _{GS} =0V			1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V			±10	μA
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} =10V, I _D =500mA		2.1	3	Ω
		V _{GS} =4.5V, I _D =200mA		2.2	4	
Forward Transconductance	g _{FS}	V _{DS} =5V, I _D =300mA		300		mS
Gate Resistance	R _g	f=1 MHz, Open drain		130		Ω
Diode Characteristics						
Continuous Body Diode Current	I _S				0.34	A
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =300mA			1.3	V
Reverse Recovery Time	t _{rr}	I _F =300mA, dI _F /dt=100A/μs		11		ns
Reverse Recovery Charge	Q _{rr}			2.6		nC
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} =10V,V _{GS} =0V,f=1MHz		16		pF
Output Capacitance	C _{oss}			4.4		
Reverse Transfer Capacitance	C _{rss}			3		
Total Gate Charge	Q _g	V _{DS} =30V,V _{GS} =10V,I _D =300mA		0.88		nC
Gate-Source Charge	Q _{gs}			0.15		
Gate-Drain Charge	Q _{gd}			0.25		
Turn-On Delay Time	t _{d(on)}	V _{DD} =30V,V _{GS} =10V, R _G =50Ω, R _L =250Ω		3		ns
Turn-On Rise Time	t _r			4		
Turn-Off Delay Time	t _{d(off)}			11		
Turn-Off Fall Time	t _f			31		

Curve Characteristics

Fig.1 - Typical Output Characteristics

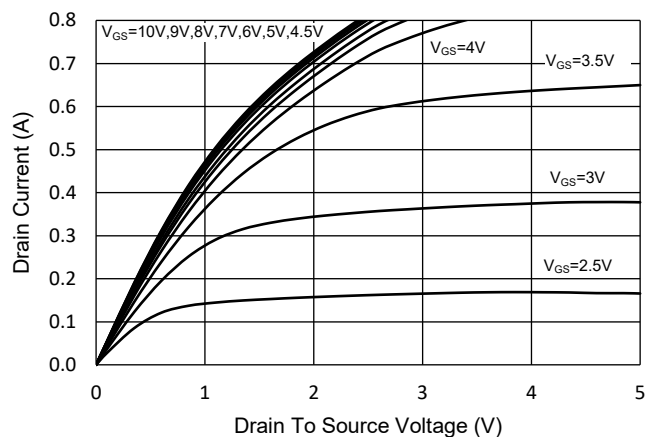


Fig.2 - Transfer Characteristic

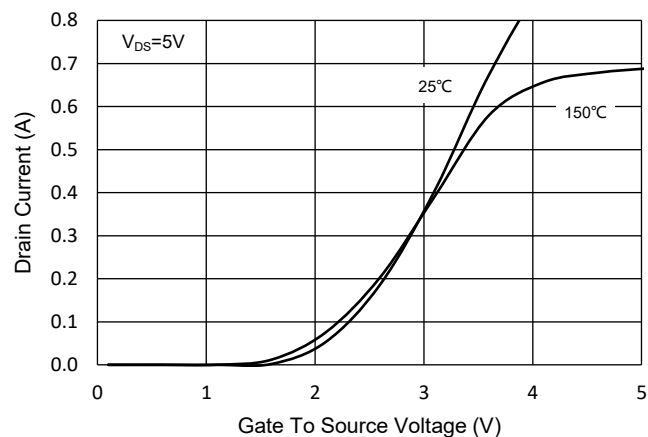


Fig.3 - $R_{DS(ON)}$ - V_{GS}

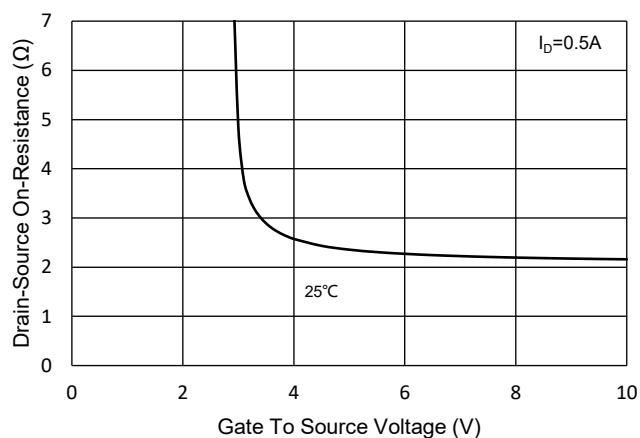


Fig.4 - $R_{DS(ON)}$ - I_D

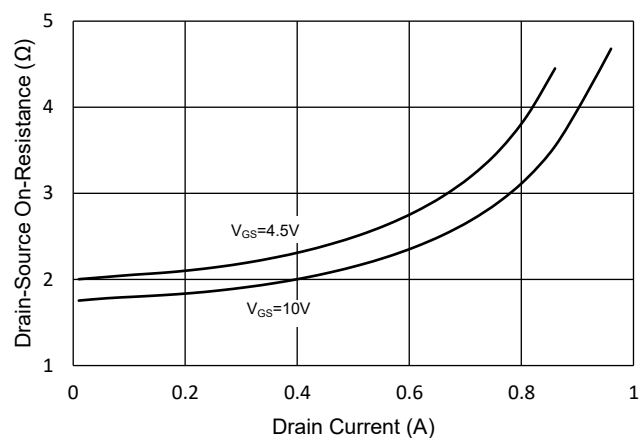


Fig.5 - Capacitance Characteristics

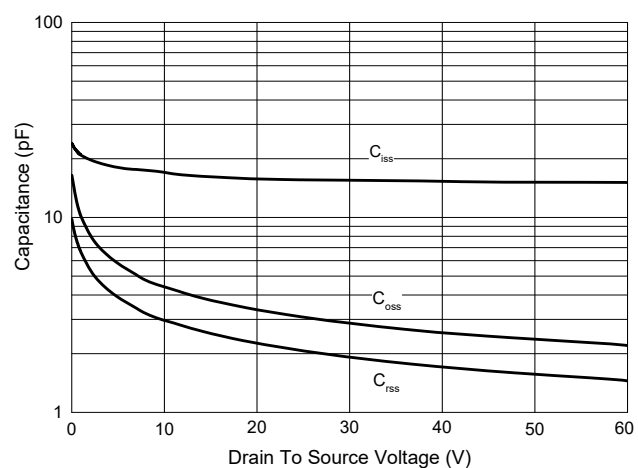
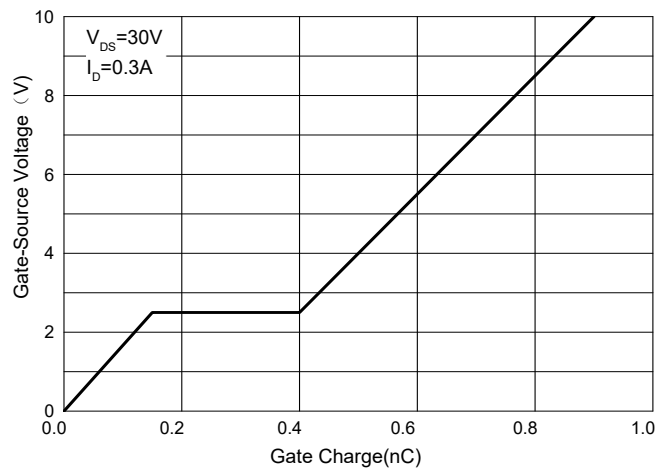


Fig.6 - Gate Charge



Curve Characteristics

Fig.7 - Normalized Threshold Voltage

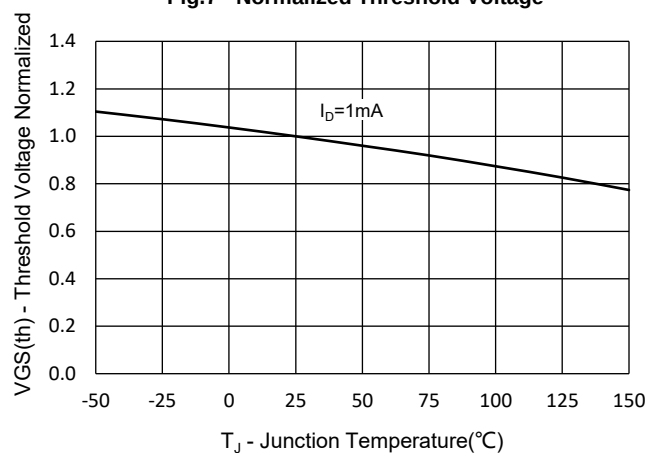


Fig.8 - Normalized On Resistance Characteristics

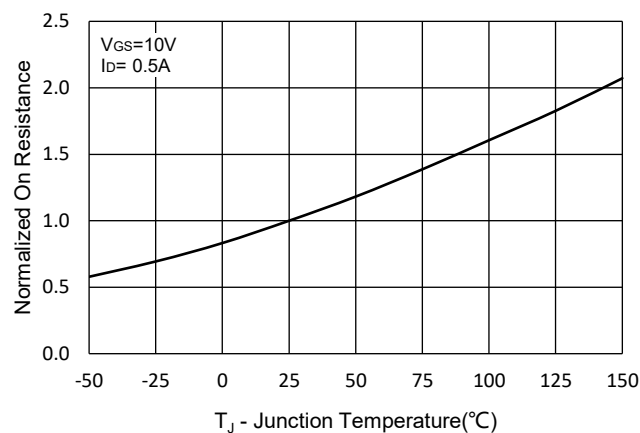


Fig.9 - $I_S - V_{SD}$

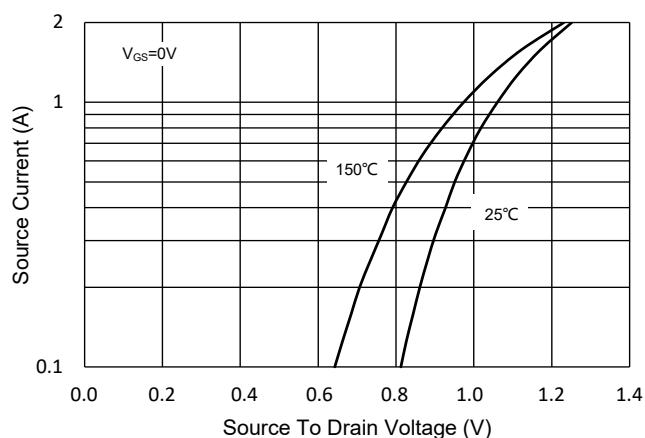


Fig.10 - Drain Current

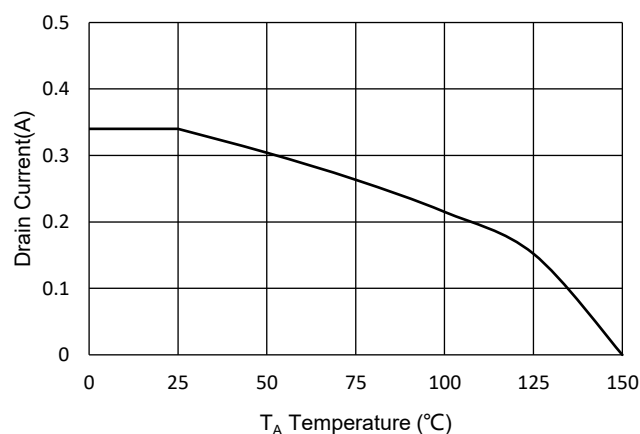
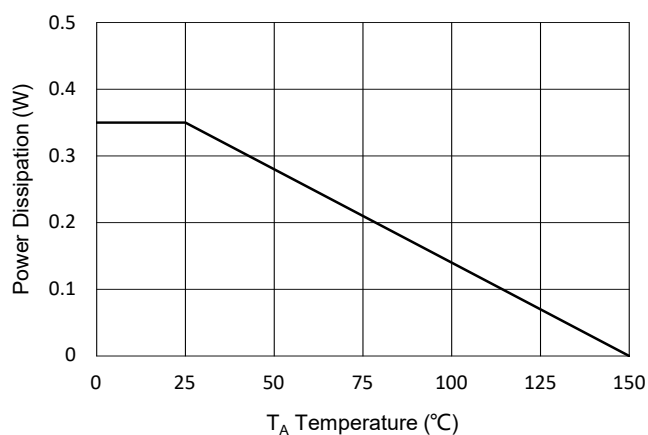


Fig.11 - PD Dissipation



Ordering Information

Device	Packing
Part Number-TP	Tape&Reel: 3Kpcs/Reel
Part Number-13P	Tape&Reel: 10Kpcs/Reel
Part Number-TPQ2	Tape&Reel:3Kpcs/Reel

For packaging details, go to our website at <https://www.mccsemi.com/pdf/ProductPackaging/SOT-363%20Package.pdf>

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